PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT3688515

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ANDREW D STRACHAN	01/04/2016
ALEXEI SADOVNIKOV	12/23/2015
GANG XUE	12/23/2015
DENING WANG	01/04/2016

RECEIVING PARTY DATA

Name:	TEXAS INSTRUMENTS INCORPORATED			
Street Address:	12500 TI BOULEVARD			
Internal Address:	M/S 3999			
City:	DALLAS			
State/Country:	TEXAS			
Postal Code:	75243			

PROPERTY NUMBERS Total: 1

Property Type	Number					
Application Number:	14991881					

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-479-3373

Email: uspto@ti.com,swalsh@ti.com

Correspondent Name: TEXAS INSTRUMENTS INCORPORATED

Address Line 1: 12500 TI BOULEVARD

Address Line 2: M/S 3999

DALLAS, TEXAS 75243 Address Line 4:

Tatal Alla alamanata d	
DATE SIGNED:	01/08/2016
SIGNATURE:	/Shawn T. Walsh/
NAME OF SUBMITTER:	SHAWN T. WALSH
ATTORNEY DOCKET NUMBER:	TI-75677

Total Attachments: 4

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source=TI-75677_Assignment_signed#page2.tif
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WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3899, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s). _______, filed ______;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereimbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE	LOW DYNAMIC RESISTANCE LOW CAPACITANCE DIODES					
NONPROVISIONAL APPLICATION NO.		FILING DATE				

SIGNATURE OF INVENTOR	ASL
PRINTED NAME OF INVENTOR	Andrew D Strachan
DATE	01 104 116
RESIDENCE (CITY AND STATE)	Santa Clara, CA

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain in new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s). _______, filed ______;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, little and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	LOW DYNAMIC RESISTANCE LOW CAPACITANCE DIODES				
NONPROVISIONAL APPLICATION NO.	FILING DATE				

SIGNATURE OF INVENTOR	Allor Sl
PRINTED NAME OF INVENTOR	Alexei Sadovnikov
DATE	12-23-2015
RESIDENCE (CITY AND STATE)	Sunnyvale, CA

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

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IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	LOW DYNAMIC RESISTANCE LOW GAPACITANCE DIODES				
NONPROVISIONAL APPLICATION NO.	FILING DATE				
SIGNATURE OF INVENTOR					
PRINTED NAME OF INVENTOR	Gang Xue				
DATE	12/2)/2015				
RESIDENCE (CITY AND STATE)	San Jose, CA				

V	VHEREAS, I, th	ie undersigned	t inventor (or	one of the	undersigne	ed joint is	nventors), (of residence	e as listed,	having	invented	certain
	seful improvem											

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

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IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	LOW DYNAMIC RESISTANCE LOW CAPACITANCE DIODES					
NONPROVISIONAL APPLICATION NO.		FILING DATE				

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Dening Wang
DATE	1/4/2016
RESIDENCE (CITY AND STATE)	McKinney, TX

PATENT REEL: 037444 FRAME: 0504

RECORDED: 01/08/2016